

MICRO BLADE



Advantages

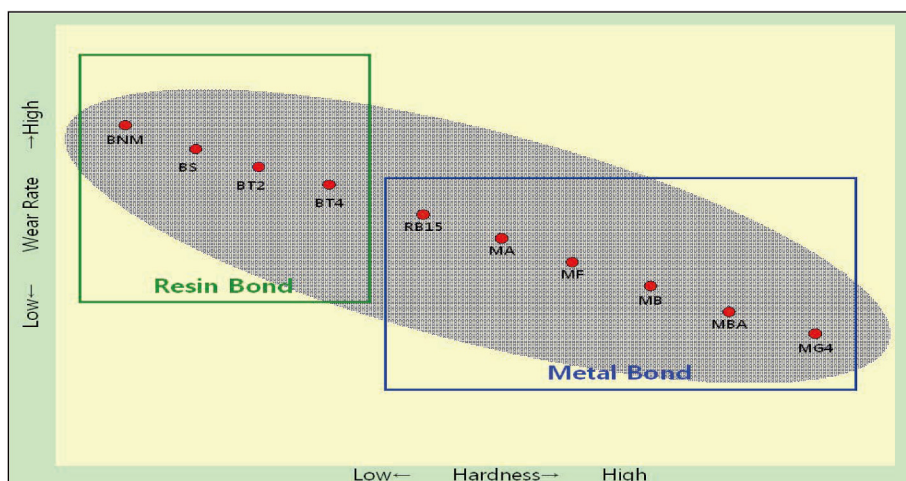
- High precision thin with superior cutting efficiency
- Maintains free cutting action at high RPM and fast feed rates
- Eliminate chipping during the sawing operation

Applications

- Sawing of packages such as QFN, FBGA, CSP, MCP, POP, PBGA
- Sawing and grooving of Ferrite, Ceramics, Glass, Quartz, Sapphire

Available Product Spec and Bond Series

Out Diameter	Minimum Thickness(mm)		
	Metal Bond	Resin Bond	Electroformed Bond
52~60 mm (2.5 inch)	0.10	0.10	0.08
75~78 (3inch)	0.15	0.15	
100~115 (4 inch)	0.15	0.20	
120~130 (5 inch)	0.20	0.25	



EHWA DIAMOND IND. CO. LTD.

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Gyeonggi-do, 18145, Korea
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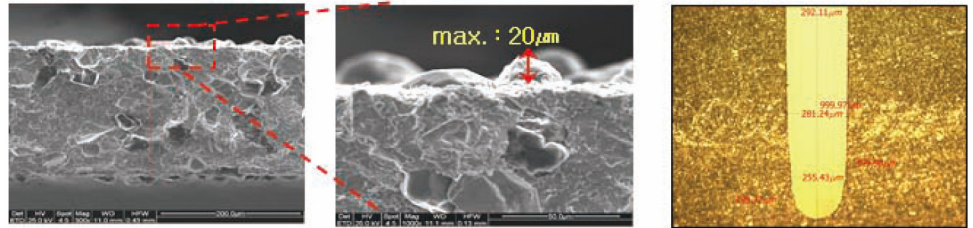
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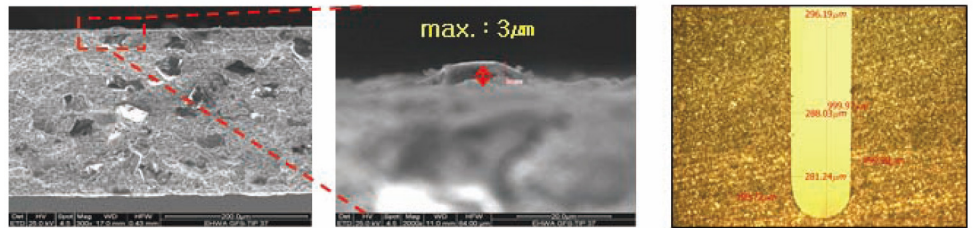


New Product (Metal & Resin Blade)

- No diamond exposure of blade surface type
- Excellent cutting quality at Cu burr, Chipping and shape maintaining
- Superior blade life time and hardness than conventional blade

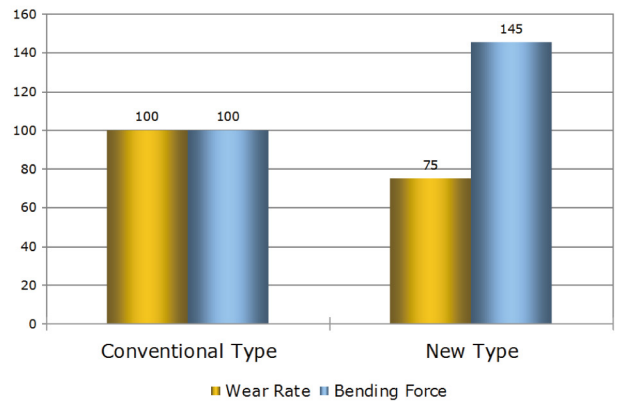


[Conventional Blade Surface and edge shape deformation]



[New Blade Surface and edge shape deformation]

Cutting surface of the PKG



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